

IN THE CLAIMS:

Claims 3 and 8 have been amended herein. All of the pending claims 1 through 11 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (Original) An electronic device package comprising:
a transparent substrate;
a flexible substrate having a mounting portion and a backing portion, the mounting portion having a central aperture and secured to a surface of the transparent substrate with the transparent substrate extending over the central aperture;
a plurality of conductive traces, each conductive trace of the plurality of conductive traces having a first attachment point on a first side of the flexible substrate and located substantially adjacent the central aperture of the mounting portion, and a second attachment point located on the backing portion on a second side of the flexible substrate; and
an optically interactive electronic device having at least one bond pad, the optically interactive electronic device mounted to the mounting portion of the flexible substrate by a bond between the first attachment point of a conductive trace of the plurality of conductive traces and the at least one bond pad.

2. (Previously presented) The electronic device package of claim 1, further comprising a rigid substrate secured to the backing portion of the flexible substrate.

3. (Currently amended) The electronic device package according to claim 1, further comprising:
a bead of sealant material contacting at least one side of the optically interactive electronic device and the first-surface-side of the flexible substrate.

4. (Original) The electronic device package according to claim 3, wherein the bead of sealant material comprises one of epoxy and silicone.

5. (Previously presented) The electronic device package according to claim 1, wherein the backing portion of the flexible substrate is adhesively attached to a back surface of the optically interactive electronic device.

6. (Previously presented) The electronic device package according to claim 1, further comprising:

at least one stand-off structure disposed between and adhered to the backing portion and the mounting portion of the flexible substrate.

7. (Original) The electronic device package according to claim 1, wherein the second attachment points of the plurality of conductive traces are formed in an array pattern on the backing portion on the second side of the flexible substrate.

8. (Currently amended) The electronic device package according to claim 1, further comprising:

a discrete conductive element attached to the second attachment point of the conductive trace of the plurality of conductive traces.

9. (Original) The electronic device package according to claim 8, wherein the discrete conductive element comprises one of a solder ball, a solder column, a conductive epoxy, and a conductor-filled epoxy.

10. (Original) The electronic device package according to claim 1, wherein the optically interactive electronic device comprises an image sensor.

11. (Original) The electronic device package according to claim 1, wherein the transparent substrate comprises a single substrate having a plurality of optically interactive electronic devices mounted thereto.

IN THE DRAWINGS:

The attached sheets of drawings include changes to FIGS. 6, 9, 13, 15B and 16. These sheets, which include FIGS. 5, 6, 9, 10, 13, 15A-15B and 16, replace the original sheets including FIGS. 6, 9, 13, 15B and 16.

Specifically, FIGS. 6, 9, 13 and 16 have been revised to correct the spelling of the word "DISCRETE" in boxes 106, 206, 308, and 408, respectively. These corrections were previously made in a Preliminary Amendment filed on October 9, 2003. FIG. 15B has been revised to lengthen the lead line extending from reference numeral --80--; and FIG. 16 has been revised to delete the "hyphen" mark ("-") between "BACKING" and "PORTION" within box 406. No new matter has been added.